



Specification

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Model No. : **SGP.18c**

Part No. : **SGP.1575.18.4.C.02**

Specification No : **SP03AB15751-0010 (03A28B640020420)(SMA1575B)V03**

Product Name : **GPS SMT Patch Antenna**

Features : 18mm*18mm*4.5mm
1575MHz Centre Frequency
Patent Pending

RoHS ✓

Photo :



REVISION STATUS

Version	Date	Page	Revision Description	Prepared	Approved
01	17 th July 2008	All	New format	TW Product Centre	Ronan Quinlan
02	9th July 2009	All	New Version	TW Product Centre	Ronan Quinlan

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1.0 Introduction

This ceramic GPS patch antenna is based on smart **XtremeGain™** technology. It is mounted via SMT process and has been selected as optimal solution for the 45*45mm ground plane.

2.0 Key Antenna Performance Indicators

Original Patch Specification tested on 45mm ground plane

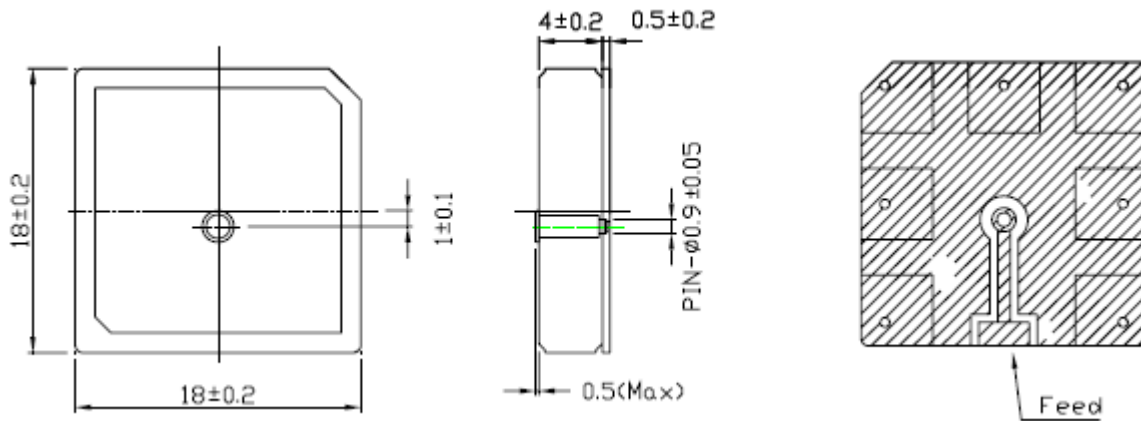
No	Parameter	Specification	
1	Range of Receiving Frequency	1575MHz +/- 1.023MHz	
2	Center Frequency**	1575MHz ± 3MHz when tested on a 45mm ² Ground Plane	
3	Bandwidth	5MHz min with Return Loss ≤-10dB	
4	VSWR	1.5 max	
5	Gain at Zenith	1.0 dBic typ.	
6	Gain at 10° Elevation	-3.0 dBic typ.	
7	Impedance	50 Ω	
8	Axial Ratio	4.0 dB max	
9	Polarization	Right Hand Circular Polarization	
10	Frequency Temperature Coefficient	0 ± 20 ppm/ °C max	@ -40°C to +105°C
11	Operating Temperature	-40°C to +105°C	

****Changes in user groundplane and environment will offset centre frequency**



3.0 Mechanical Specifications

3.1 Dimensions and Drawing

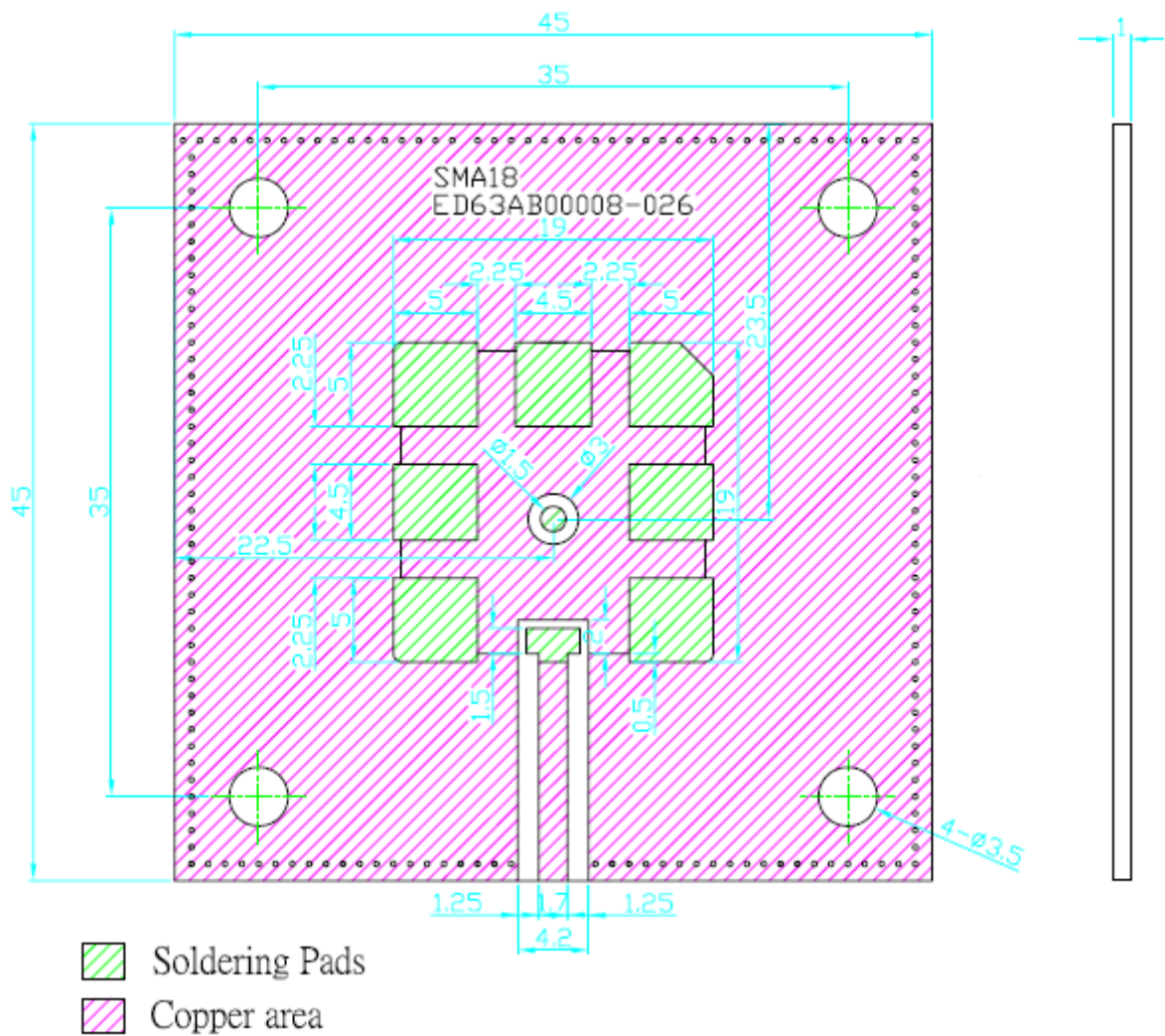




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3.2 Antenna footprint (view from underneath)

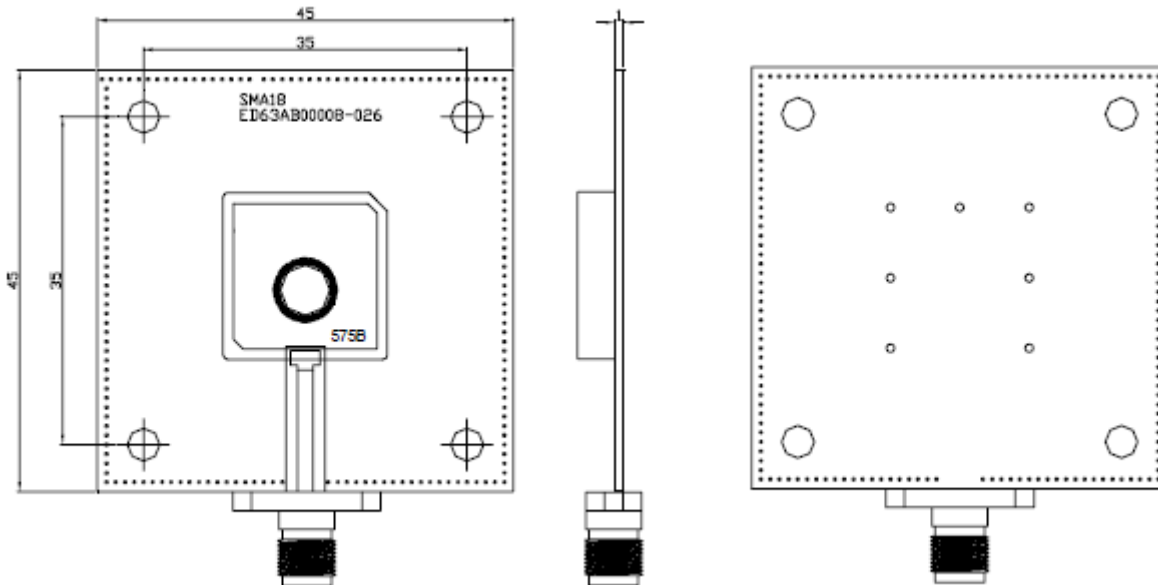
Please note: solder mask has been added to all areas except gold solder areas (green highlighted areas), this will prevent Feed points connecting to ground of main PCB



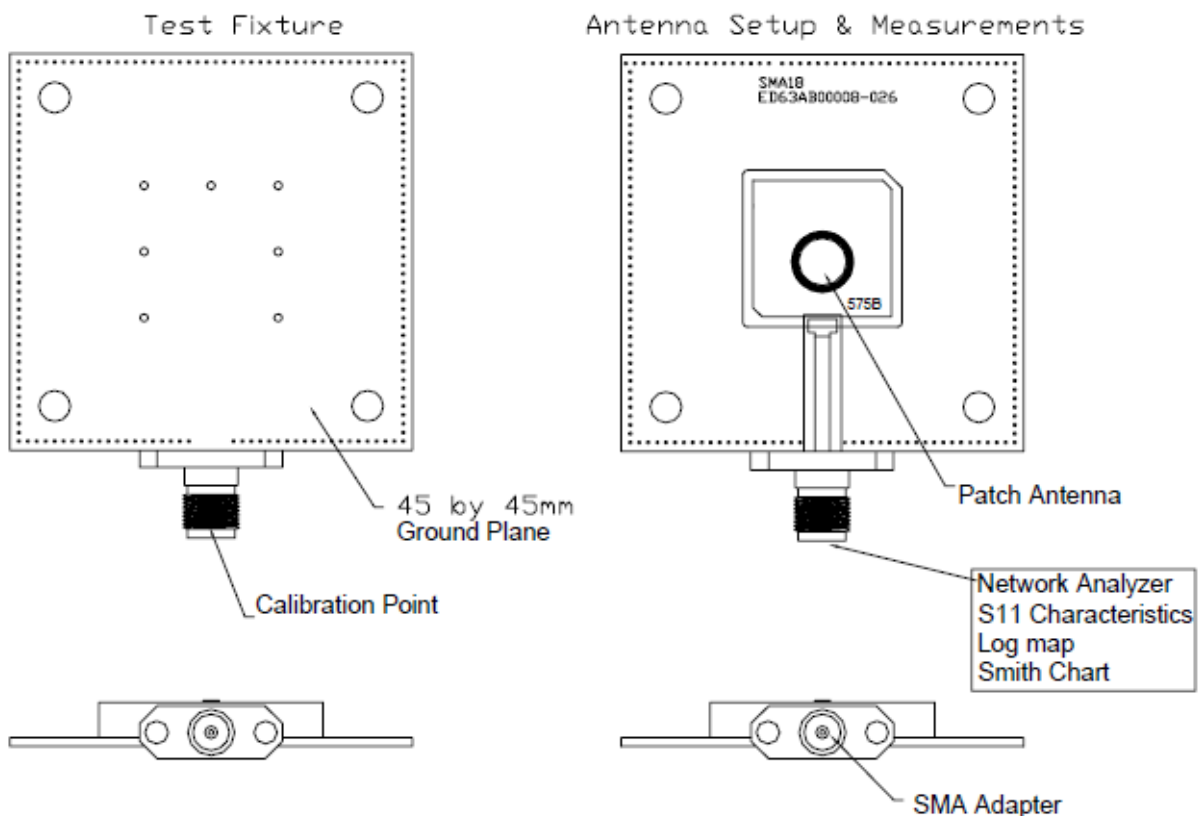


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3.3 Test Jig and Dimension

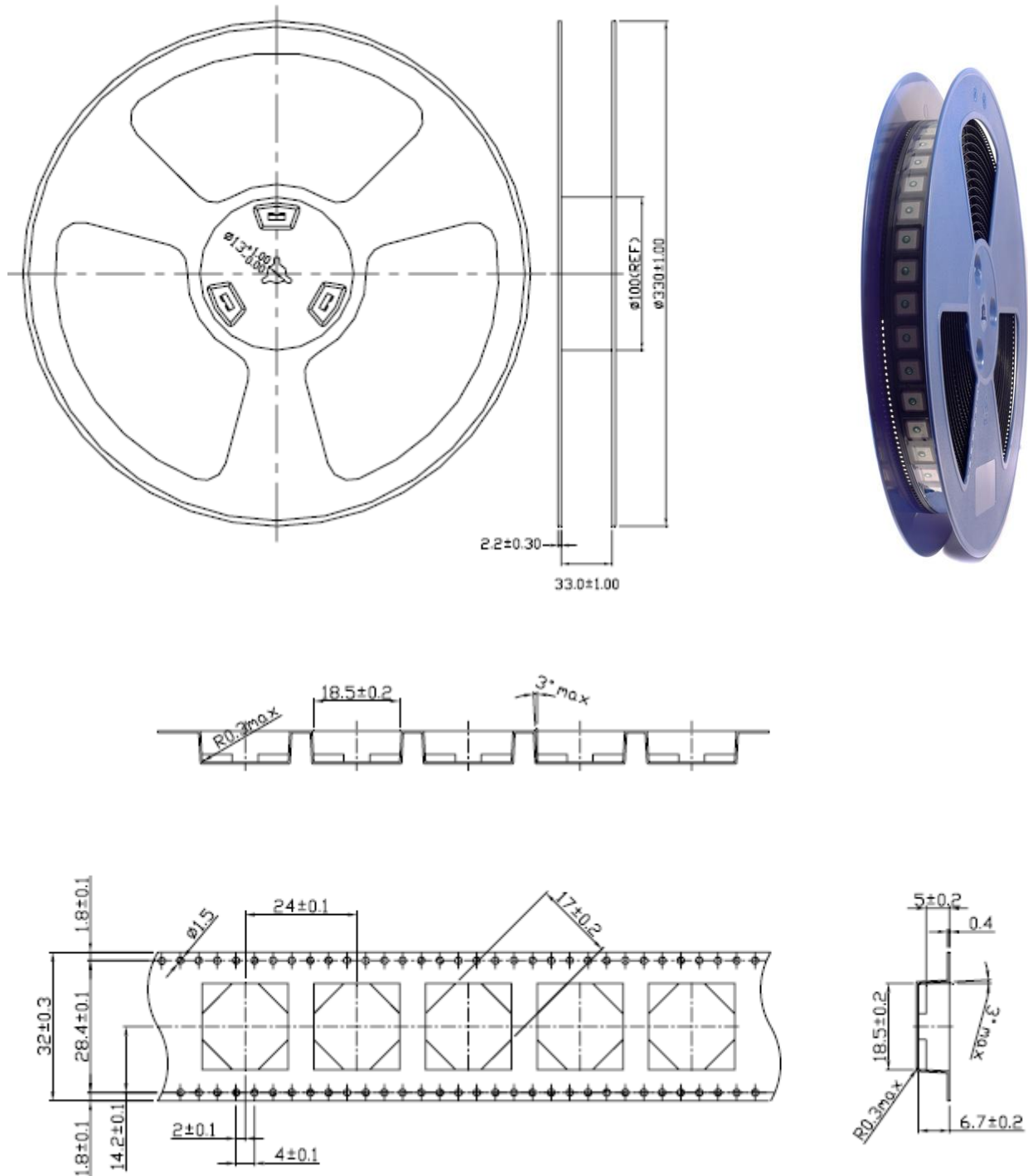


3.4 Test Fixture set up and measurements





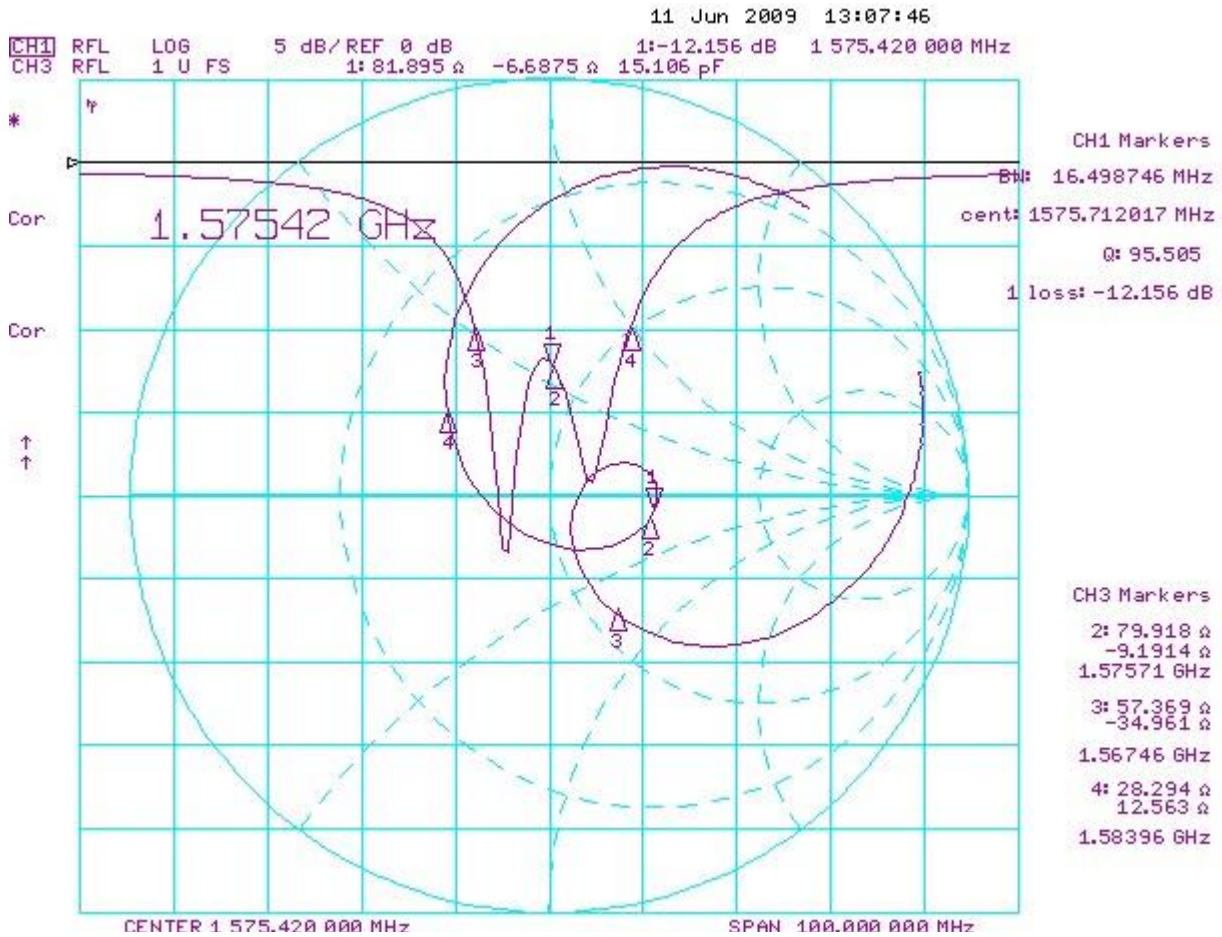
3.5 Delivery Mode





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4. Smith Chart



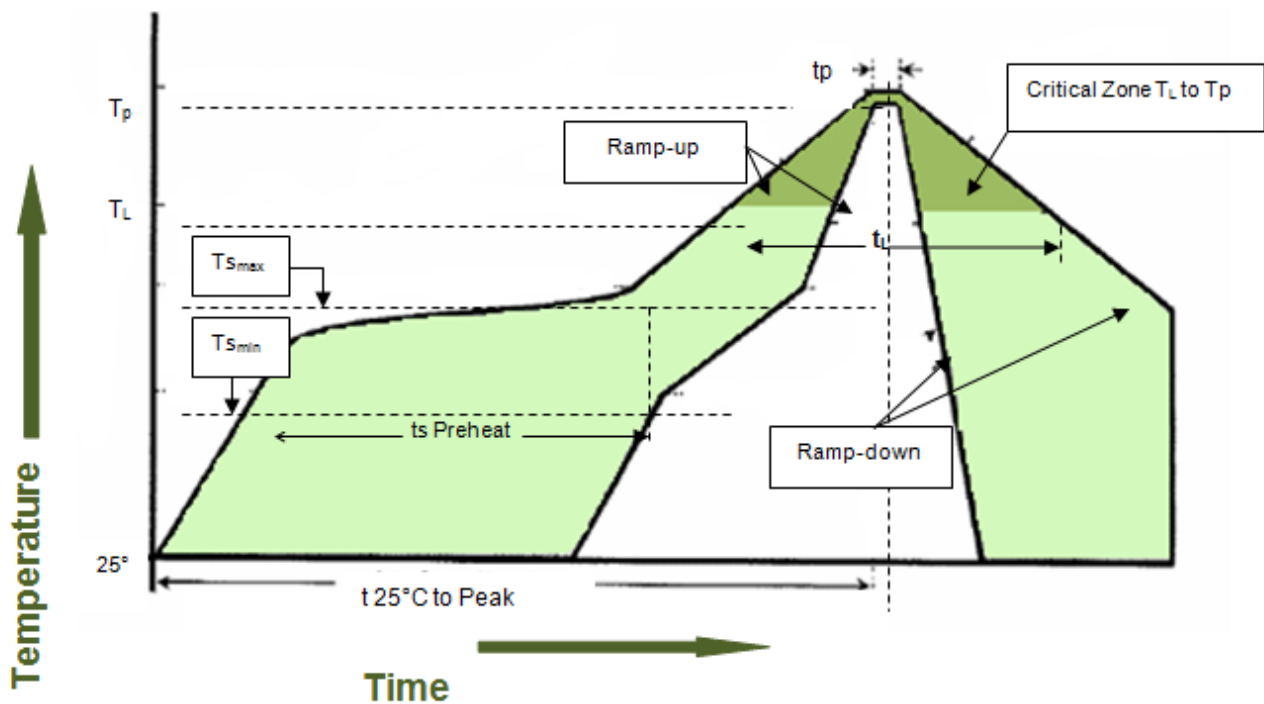


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5.0 Recommended Reflow Temperature Profile

The SGP.18c can be assembled following either Sn-Pb or Pb-Free assembly processes. The recommended soldering temperatures are as follows:

Phase	Profile Features	Sn-Pb Assembly	Pb-Free Assembly (SnAgCu)
Ramp-Up	Avg Ramp-Up Rate (T _{smax} to T _p)	3°C/second (max)	3°C/second (max)
Preheat	Temperature Min (T _{smin})	100°	100°
	Temperature Max (T _{smax})	150°	150°
	Time (t _{smin} to t _{smax})	60-120 seconds	60-120 seconds
Reflow	Temperature (T _L)	183°C	217°C
	Total Time Above T _L b(t _L)	60-150 seconds	60-150 seconds
Peak	Temperature (T _p)	235°C	260°C
	Time (t _p)	10-30 seconds	20-40 seconds
Ramp-Down	Rate	6°C/second (max)	6°C/second (max)
Time from 25°C to peak Temperature		6 minutes max	8 minutes max



Temperature profile – (green area) for the assembly process in reflow ovens